

Assembly Location and Mold Compound Change for QFN Packages

Product Change Notice

PCN0806 (v1.0) September 12, 2008

Overview

This notice describes two changes to the ARINC 429 and MIL-STD 1553 family of devices which are manufactured in QFN packages:

- Assembly plant location change for all QFN Packages (40PCS, 44PCS, and 64PCS) from current CARSEM,
 Malaysia location to CEI, Thailand location. (Quality)
- Change of mold compound material to Nitto GE-7470L-A to ensure use of the same mold compound across all QFN packages assembled at CEI, Thailand. (Form)

Description

The QFN package assembly is being moved from the CARSEM, Malaysia location to the CEI, Thailand location. As part of this transition, the molding compound used for all QFN packages is also being changed from Sumitomo G770H to Nitto GE-7470L-A.

The QFN package assembly is fully qualified at the CEI, Thailand location. (See Qualification Data in Table 2) CEI, Thailand has been a qualified supplier of Holt plastic parts for over 10 years and is ISO/ TS 16949 certified.

These consolidations are designed to make QFN assembly more efficient and timely, enabling smooth supply to Holt's customers. There is no change to the external physical dimensions of the package. Holt's qualified subcontractor, CEI, will assemble the package/product to meet all of the existing visual, dimensional, electrical, quality and reliability specifications.

There is no change to Fit, Function, or Reliability of these devices.

Reason

The QFN package at CEI, Thailand is being added to ensure guaranteed supply of QFN package configuration device products.

Products Affected

Table 1 summarizes the products affected by this PCN. All parts listed are affected by this change.

Table 1: Products Affected

HI-3582PCI	HI-3583PCI-10	HI-1565PCI	HI-1568PCI	HI-1574PCI	HI-1579PCI
HI-3582PCIF	HI-3583PCIF-10	HI-1565PCIF	HI-1568PCIF	HI-1574PCIF	HI-1579PCIF
HI-3582PCT	HI-3583PCT-10	HI-1565PCT	HI-1568PCT	HI-1574PCT	HI-1579PCT
HI-3582PCTF	HI-3583PCTF-10	HI-1565PCTF	HI-1568PCTF	HI-1574PCTF	HI-1579PCTF
HI-3582PCI-10	HI-3584PCI	HI-1566PCI	HI-1570PCI	HI-1575PCI	HI-6110PCI
HI-3582PCIF-10	HI-3584PCIF	HI-1566PCIF	HI-1570PCIF	HI-1575PCIF	HI-6110PCIF
HI-3582PCT-10	HI-3584PCT	HI-1566PCT	HI-1570PCT	HI-1575PCT	HI-6110PCT
HI-3582PCTF-10	HI-3584PCTF	HI-1566PCTF	HI-1570PCTF	HI-1575PCTF	HI-6110PCTF
HI-3583PCI	HI-3584PCI-10	HI-1567PCI	HI-1573PCI		
HI-3583PCIF	HI-3584PCIF-10	HI-1567PCIF	HI-1573PCIF		
HI-3583PCT	HI-3584PCT-10	HI-1567PCT	HI-1573PCT		
HI-3583PCTF	HI-3584PCTF-10	HI-1567PCTF	HI-1573PCTF		

Traceability

A Date Code and Country of Origin facilitate package traceability. Parts from Table 1 will be shipped with a Country of Origin of Thailand and a Date Code of 0810 or later, beginning October 12, 2008. Product from the CARSEM, Malaysia location will stop shipping upon inventory depletion.

Note: Starting October 12, 2008, devices from either assembly house can be shipped at Holt's discretion until inventory from finished goods is exhausted.



Qualification Data

Reliability Test	Requirement	QR-8033 Rev 1.0
Device Characterization	Final Test yield analysis over -55°C and +125°C temperature extremes.	205/0
Precondition (PC)	MSL 3	11/0
PC + HAST	96 hrs	60/0
PC + Autoclave	96 hrs	45/0
PC + Temp Cycle	1000 cycles	45/0
PC + HTS	1000 hrs	55/0

Response

Note: In accordance with JESD46-C, this change is deemed accepted by the customer if no acknowledgement is received within 30 days from this notice.

No response is required. For additional information or questions, please contact:

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Additional Documentation

Below is a list of documents that are associated with this notice:

o QR-8033 Rev. 1.0 QFN-64 CEI

Revision History

The following table shows the revision history for this document.

Date	Version	Revision Description
9/12/08	1.0	Initial Release